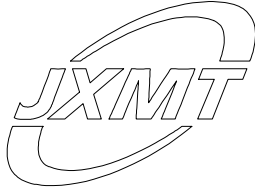
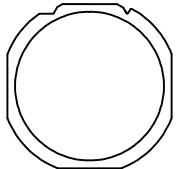
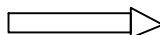
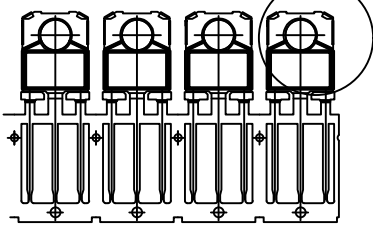
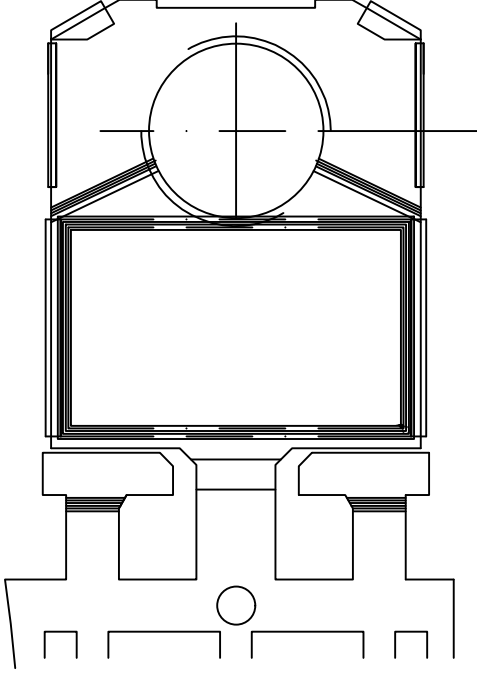


Bonding Diagram

	安徽积芯微电子科技有限公司 Anhui Jixin Microelectronics Technology Ltd.					
	BD No.				版本	
	Device		Package	TO247A-3L	Customer	
装片方向 	引线框传输方向 				客户确认	
						
BOM	TYPE					
	Die Name	Wafer Size (inch)	Die Size Without SL(μm)	Gate Pad Size (μm)	Scribe Line (μm)	Die Thickness (μm)
芯片CHIP						
基岛尺寸 (mm) L/F Pad Size	12.5 * 7.42	栅极线材规格 Gate Wire Spec.		电镀方式 Plating Type		晶圆背金 Wafer back material
焊线方式 Wire Type		源极线材规格 Source Wire Spec.		总线数 Total Qty		
产品等级 MSL Level		线图来源 BD source				晶圆正面金属 Wafer top material
备注 Remark						
制图日期		有效期	<input type="checkbox"/> 永久 <input type="checkbox"/> 六个月 <input type="checkbox"/> 其他			
拟制 Prepared By		审核 Checked By		批准 Approved By		文控发行章 Controlled Chapter